

● PRINTER RUSH ●

(PTO ASSISTANCE)

IPW

Application : <u>09/475104</u>	Examiner : <u>Mitchell</u>	GAU : <u>2813</u>
From : <u>TW</u>	Location : IDC FMF <u>(FDO)</u>	Date : <u>8-1-05</u>

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DOC CODE	DOC DATE	MISCELLANEOUS
<input type="checkbox"/> 1449	_____	<input type="checkbox"/> Continuing Data
<input type="checkbox"/> IDS	_____	<input type="checkbox"/> Foreign Priority
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<input type="checkbox"/> DRW	_____	
<input type="checkbox"/> OATH	_____	
<input type="checkbox"/> 312	_____	
<input checked="" type="checkbox"/> SPEC	<u>12-30-99</u>	

[RUSH] MESSAGE: Please verify

On Page 4 of the specification submitted on 12-30-99 there is a reference
on Lines 8 and 9 to Figures 3A and 3B. Figures 3A and 3B do not exist
on the drawing sheets of this application.
The spec amendment dated 9-27-01 deleted data on Page 7 but not Page 4.

Thank You
TW

[XRUSH] RESPONSE: Deleted Fig 3a-3b description

INITIALS: def

NOTE: This form will be included as part of the official USPTO record, with the Response document coded as XRUSH.
 REV 10/04

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 is a cross-sectional view of an embodiment
of an integrated circuit package of the present
5 invention;

Figures 2a-b show a process for assembling a thermal
epoxy within the integrated circuit package^d.

~~Figures 3a-b show an alternate process for assembling
the thermal epoxy within the package.~~